



Product Change Notification

Change Notification #: 117206 - 00
Change Title: Intel® Server Chassis H2204XXLRE, PCN 117206-00, Product Design, 3.5" Tool-Less Carrier Design Improvement for 2.5" Drive Support
Date of Publication: October 15, 2019

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

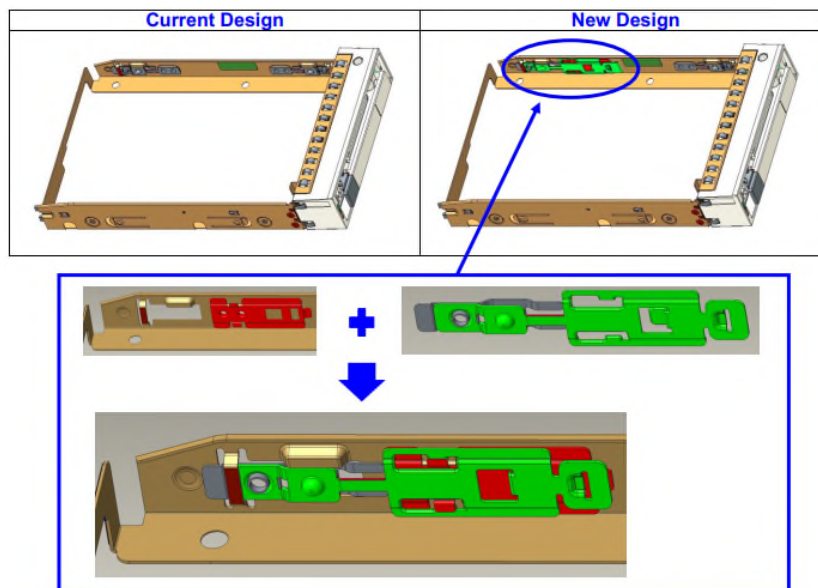
Date Customer Must be Ready to Receive Post-Conversion Material:*	October 31, 2019
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*Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is implementing an improvement on FXX35HSCAR2 3.5" tool-less drive carrier for 2.5" drive support in factory for Intel® server chassis H2204XXLRE

- New rear spring (see image in green) and new spring holder (see image in red) attached to the tool-less drive carrier.
- Removing the rear spring of 3.5" tool-less carrier when Install 2.5" SSD drive, Installing the rear spring to support 3.5" HDD.



Customer Impact of Change and Recommended Action:

Intel does not expect any other impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications. For that reason Intel recommends that the customer perform a standard level of evaluation.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
H2204XXLRE	957322	J32925-011	J32925-012

PCN Revision History:

Date of Revision:

October 15, 2019

Revision Number:

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Reason:

Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

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